

# HZM7.5FA

Silicon Epitaxial Planar Zener Diode for Surge Absorb

# HITACHI

ADE-208-616 (Z)

Rev 0

Apr. 1998

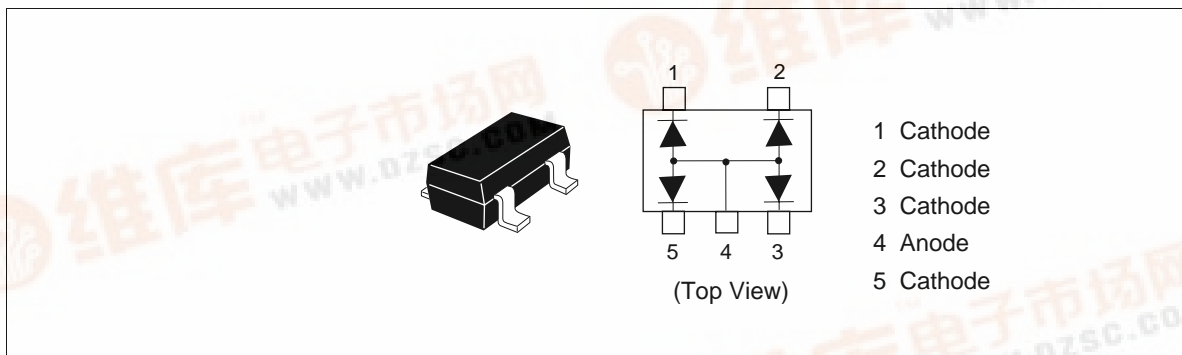
## Features

- HZM7.5FA has four devices, and can absorb external + and -surge.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HZM7.5FA	75A	MPAK-5

## Outline



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## HZM7.5FA

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### Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd <sup>*1</sup>	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note 1. Four device total, With P.C board.

### Electrical Characteristics (Ta = 25°C) <sup>\*2</sup>

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V <sub>Z</sub>	7.06	—	7.84	V	I <sub>Z</sub> = 5 mA, 40ms pulse
Reverse current	I <sub>R</sub>	—	—	2	μA	V <sub>R</sub> = 4V
Capacitance	C	—	—	125	pF	V <sub>R</sub> = 0V, f = 1 MHz
Dynamic resistance	r <sub>d</sub>	—	—	30	Ω	I <sub>Z</sub> = 5 mA
ESD-Capability <sup>*1</sup>	—	30	—	—	kV	C = 150pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes 1. Failure criterion ; IR > 2 μA at VR = 4V.

2. Per one device.

Main Characteristic

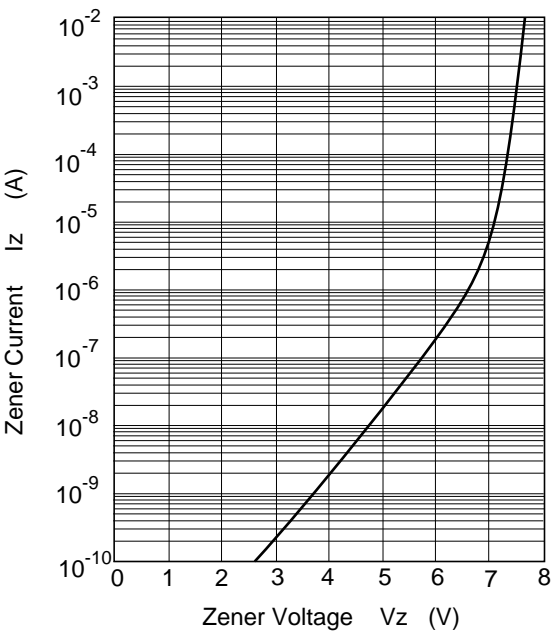


Fig.1 Zener current Vs. Zener voltage

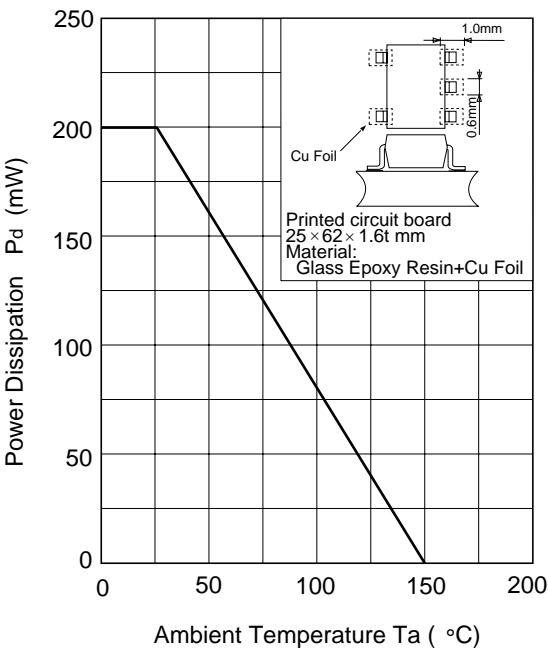


Fig.2 Power Dissipation Vs. Ambient Temperature

**HZM7.5FA**

**Main Characteristic**

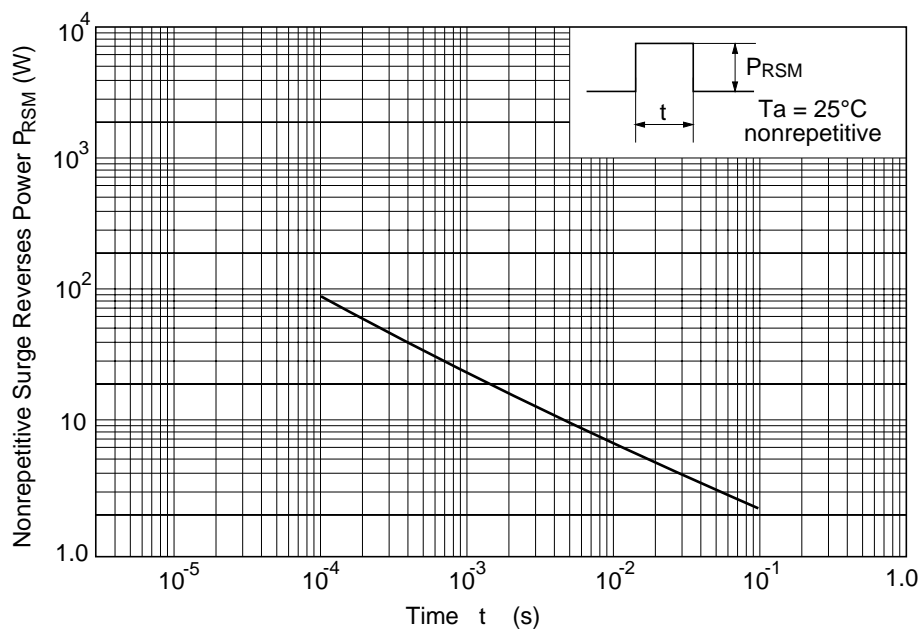


Fig.3 Surge Reverse Power Ratings

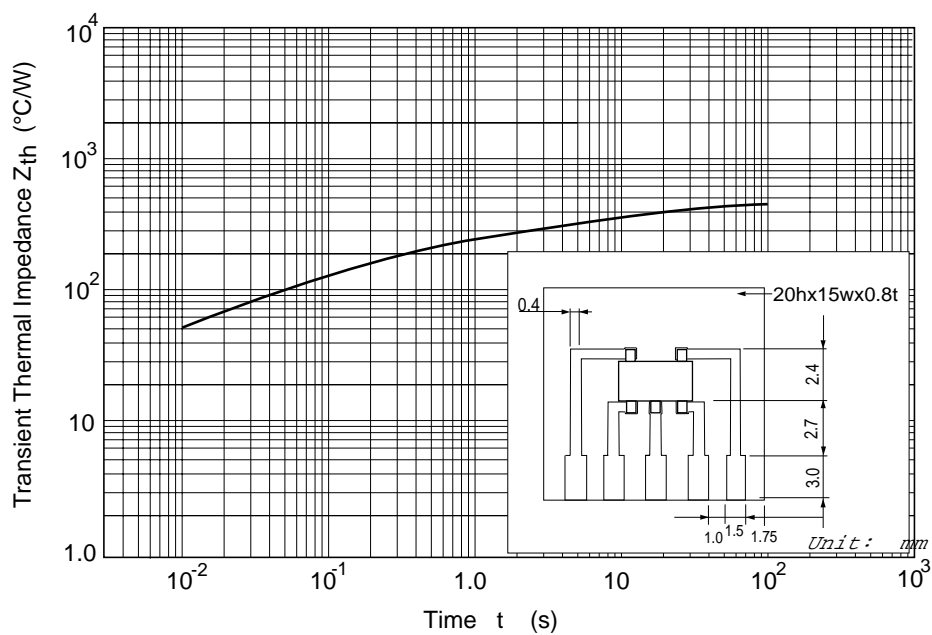
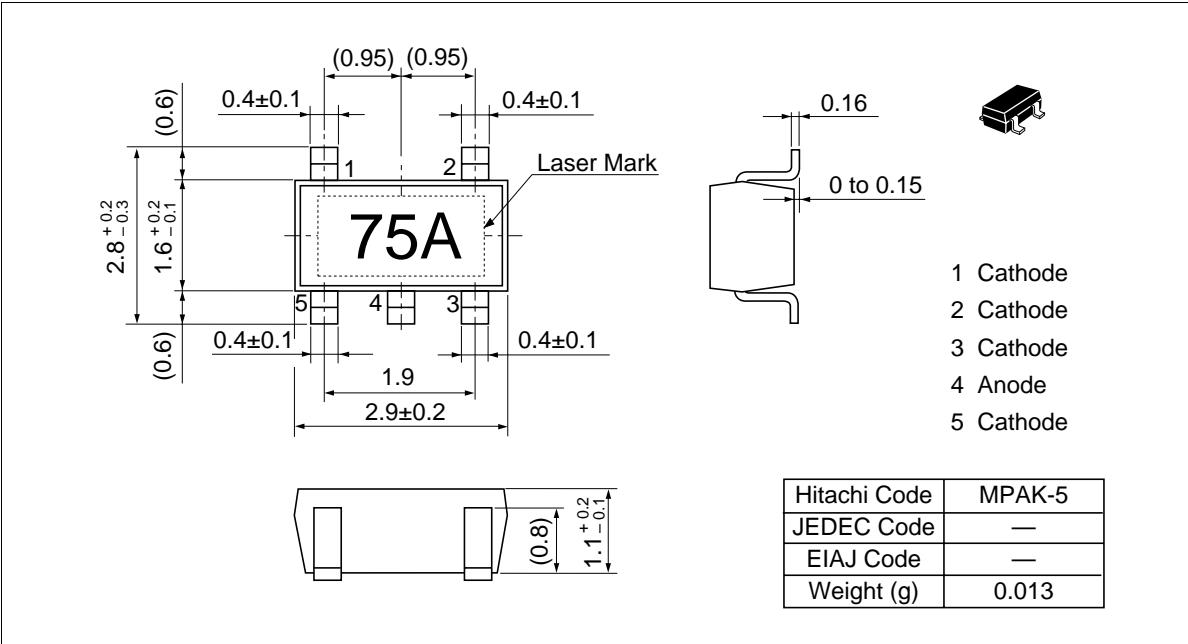


Fig.4 Transient Thermal Impedance

HZM7.5FA

Package Dimensions

Unit : mm



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